

AMENDMENTS TO THE CLAIMS

Claims 1-35 (Cancelled)

Claim 36 (New) An apparatus for polishing a substrate having a surface on which a first layer and a second layer are formed, comprising:

- a polishing table having a polishing surface;
 - a substrate carrier having a lower surface for holding the substrate and bringing the substrate into contact with said polishing surface;
 - a pivotal shaft for rotatably supporting said substrate carrier;
 - an attitude control mechanism for keeping said lower surface of said substrate carrier parallel with the polishing surface;
 - a liquid supply nozzle for supplying a first polishing liquid while polishing the first layer, and for supplying a second polishing liquid while polishing the second layer;
 - a first nozzle for providing water toward said polishing surface for cleaning said polishing surface after polishing the first layer and before polishing the second layer;
 - a thickness measurement device for determining an end point of polishing of the first layer, said thickness measurement device being positioned at an outer peripheral portion of said polishing table; and
 - a second nozzle for providing water toward the surface of the substrate for cleaning the surface after being polished;
- wherein said substrate carrier is set to extend outwardly of the outer peripheral portion of the polishing table during polishing operation.

Claim 37 (New) An apparatus for polishing a substrate having a surface on which a first layer and a second layer are formed, comprising:

- a polishing table having a polishing surface;
- a substrate carrier having a lower surface for holding the substrate and bringing the substrate into contact with said polishing surface;

a pivotal shaft for rotatably supporting said substrate carrier;
an attitude control mechanism for keeping said lower surface of said substrate carrier parallel with said polishing surface;
a liquid supply nozzle for supplying a first polishing liquid while polishing the first layer, and for supplying a second polishing liquid while polishing the second layer;
a first nozzle for providing water toward said polishing surface for cleaning said polishing surface after polishing the first layer and before polishing the second layer;
a thickness measurement device for determining an end point of polishing of said first layer, said thickness measurement device being positioned at an outer peripheral portion of said polishing table; and
a second nozzle for providing water toward the surface of the substrate for cleaning the surface after being polished.

Claim 38 (New) An apparatus claimed in claim 37, further comprising an actuator for altering a force acting to urge the surface of the substrate against the polishing surface during polishing of the first layer.

Claim 39 (New) An apparatus claimed in claim 38, wherein said substrate carrier is set to extend outwardly of the outer peripheral portion of the polishing table during polishing operation.

Claim 40 (New) An apparatus for polishing a substrate having a surface on which a first layer and a second layer are formed, comprising:

a polishing table having a polishing surface;
a substrate carrier having a lower surface for holding the substrate and bringing the substrate into contact with said polishing surface;
an attitude control mechanism for keeping said lower surface of said substrate carrier parallel with said polishing surface;

a liquid supply nozzle for supplying a first polishing liquid while polishing the first layer, and for supplying a second polishing liquid while polishing the second layer;

a first nozzle for providing water toward said polishing surface for cleaning said polishing surface after polishing the first layer and before polishing the second layer; and

a thickness measurement device for determining an end point of polishing of the first layer, said thickness measurement device being positioned at an outer peripheral portion of said polishing table.

Claim 41 (New) An apparatus claimed in claim 40, further comprising a second nozzle for providing water toward the surface of the substrate for cleaning the surface of the substrate after being polished.

Claim 42 (New) An apparatus claimed in claim 41, wherein said substrate carrier is set to extend outwardly of the outer peripheral portion of said polishing table during polishing operation.

Claim 43 (New) An apparatus for polishing a substrate on which a first layer and a second layer are formed, comprising:

a polishing table having a polishing surface;

a substrate carrier having a lower surface for holding a substrate and bringing the substrate into contact with said polishing surface;

an attitude control mechanism for keeping said lower surface of said substrate carrier parallel with said polishing surface;

a liquid supply nozzle for supplying a polishing liquid while polishing the first layer, and while polishing the second layer;

a nozzle for providing water toward said polishing surface for cleaning said polishing surface after polishing the first layer and before polishing the second layer; and

a thickness measurement device for determining an end point of polishing of the first layer, said thickness measurement device being positioned at an outer peripheral portion of said polishing table;

wherein said substrate carrier is set to extend outwardly of an outer peripheral portion of said polishing table during polishing operation.